

Title (en)

METHOD FOR CONTACTING PARTS OF A COMPONENT INTEGRATED INTO A SEMICONDUCTOR SUBSTRATE

Title (de)

VERFAHREN ZUR HERSTELLUNG VON KONTAKTEN ZU TEILEN EINES IN EINEM HALBLEITERSUBSTRAT INTEGRIERTEN BAUELEMENTS

Title (fr)

PROCEDE DE PRODUCTION DE CONTACTS SUR LES ELEMENTS D UN COMP OSANT INTEGRE D UN SUBSTRAT DE SEMI-CONDUCTEUR

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Application

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Abstract (en)

[origin: WO2004003998A1] The invention relates to a method for contacting parts of a component integrated into a semiconductor substrate (1). According to the inventive method, a first contact hole is produced in an insulating layer (2), said contact hole being then filled with contact material (16) and connected to a line. The aim of the invention is to minimise the processes required for contacting parts of a component integrated into a semiconductor substrate. To this end, the hard mask (3) used to produce the contact hole is also used to structure the line.

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